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Application No. Not Yet Assigned Paper Dated April 13, 2006 In Reply to USPTO Correspondence of N/A Attorney Docket No. 1217-060907

Customer No. 28289 IAPO RECOPCIFIED 13 APR 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.

Not Yet Assigned

Applicants

Koichi NAGAMOTO et al.

Filed

Concurrently Herewith

Title

SURFACE-PROTECTING SHEET AND SEMICONDUCTOR WAFER LAPPING

METHOD

:

International Application No.:

PCT/JP2004/015131

International Filing Date :

14 October 2004

Priority Date(s) Claimed :

16 October 2003

MAIL STOP PCT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination, please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 this paper.

Remarks begin on page 8 of this paper.